microSDXC memory card Flash Storage Media

1. Introduction

Industrial temperature microSDXC card is designed, manufactured and tested to withstand extreme environmental conditions. Outdoor applications such as Kiosks, Gas Pumps, ATMs, Media Gateways, and Automotive/Marine. Also ideal for Internet of Things (IoT) applications to be used in the latest industrial applications.

The eXtended Capacity microSD memory card is functionally compatible with the SD memory specification but is smaller in dimension. This microSDXC memory card can also be inserted into a microSD memory card adapter and used as a standard Secure Digital memory card.

2. Part Number

SDHC Class	UHS	Capacity	Part Number
Class 10	U1	64GB	SDCIT/64GB

3. microSDXC memory card features

Table	1: microSDXC Card Fea	tures
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Design	Standard	
Contents	None (OEM Design Available)	
Security Functions	SD Security Specification Ver.3.00 Compliant (CPRM Based) *CPRM: Contents Protection for Recording Media Specification	ID, MKB Programmed
Logical Format	SD Files System Specification Ver.3.00 Compliant (exFAT Based formatted)	
Electrical	Operating Voltage: 2.7V to 3.6V (Memory Operation) Interfaces: SD Card Interface, (SD: 4 or 1bit) SPI Mode Compatible SD Physical Layer Specification Ver.3.01 Compliant	
Physical	L: 15, W: 11, T: 1.0 (mm), Weight: 0.5g (typ.) microSD Memory Card Specification Ver. 3.01 Compliant (Detailed Dimensions included at: Appendix)	
Durability	SD Physical Layer Specification Ver.3.01 Compliant microSD Memory Card Specification Ver. 3.01 Compliant	
ROHS	ROHS Compatible	

- Implementing both static and dynamic wear leveling.
- MLC NAND for endurance

4. Compatibility

Compliant Specifications

SD Memory Card Specifications

- Compliant with PHYSICAL LAYER SPECIFICATION Ver.3.01. (Part1)
- Compliant with FILE SYSTEM SPECIFICATION Ver.3.00. (Part2)
- Compliant with SECURITY SPECIFICATION Ver.3.00. (Part3)
- microSD Memory Card Specification Ver. 3.01

5. Physical Characteristics

5.1. Temperature

1) Operation Conditions

Temperature Range: $T_a = -40 \,^{\circ}\text{C}$ to +85 $^{\circ}\text{C}$

2) Storage Conditions

Temperature Range: T_{stq} = -40 °C to +85 °C

5.2. Moisture (Reliability)

1) Operation Conditions

Temperature 25 °C / 95% rel. humidity

2) Storage Conditions

Temperature 40 °C / 93% rel. humidity / 500h

5.3 Application

- 1) Hot Insertion or Removal
 - a. Kingston microSDXC Memory Card can be removed and/or inserted without powering off the host system.
- 2) Mechanical Write Protect Switch
 - a. microSDXC Memory Card has no mechanical write protect switch.

5.4 Configuration

Controller: PS8210DF

NAND: Toshiba 15nm MLC 64Gb

6. Electrical Interface Outlines

6.1. microSD Card Pins

Table 2 define the pin assignment of the microSD card.

Fig.1 describes the pin location of the microSD card.

Please refer the detail descriptions by SD Card Physical Layer Specification.

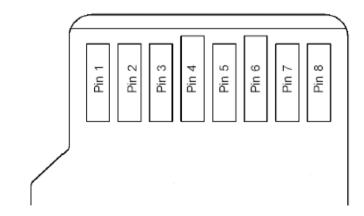


Figure 1: microSD Card Pin Assignment (Back View of Card)

Pins	SD Mode		SPI Mode			
FIIIS	Name	IO type 1	Description	Name	IO Type	Description
1	DAT2	I/O /PP	Data Line[Bit2]	RSV		
2	CD/	I/O/PP	Card Detect / Data	CS	- 1	Chip Select (neg true)
	DAT3		Line[Bit3]			
3	CMD	PP	Command/Response	DI	I	Data In
4	V_{dd}	S	Supply Voltage	V_{dd}	S	Supply Voltage
5	CLK	I	Clock	SCLK	- 1	Clock
6	V_{SS}	S	Supply voltage ground	V_{SS}	S	Supply voltage ground
7	DAT0	I/O /PP	Data Line[Bit0]	DO	O/PP	Data Out
8	DAT1	I/O /PP	Data Line[Bit1]	RSV	-	Reserved (*)

Table 2: microSD Card Pin Assignment

- 1) S: Power Supply, I: Input, O: Output, I/O: Bi-Directional, PP: IO Using Push-Pull Drivers
- (*) These Signals should be pulled up by host side with 10-100K ohm resistance in SPI Mode. Do not use NC pins.

6.2 microSD Card Bus Topology

The microSD Memory Card supports two alternative communication protocols: SD and SPI Bus Mode. Host System can choose either one of modes. Same Data of the microSD Card can read and write by both modes.

SD Mode allows the 4-bit high performance data transfer. SPI Mode allows easy and common interface for SPI channel. The disadvantage of this mode is loss of performance, relatively to the SD mode.

6.2.1 SD Bus Mode protocol

The SD bus allows the dynamic configuration of the number of data line from 1 to 4 Bidirectional data signal. After power up by default, the microSD card will use only DAT0. After initialization, host can change the bus width.

Multiplied microSD cards connections are available to the host. Common V_{dd} , V_{ss} and CLK signal connections are available in the multiple connection. However, Command, Respond and Data lined (DAT0-DAT3) shall be divided for each card from host.

This feature allows easy trade off between hardware cost and system performance. Communication over the microSD bus is based on command and data bit stream initiated by a start bit and terminated by stop bit.

Command:

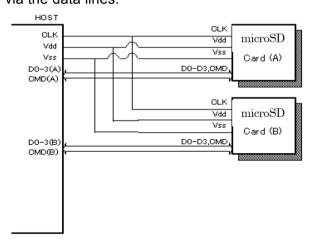
Commands are transferred serially on the CMD line. A command is a token to starts an operation from host to the card. Commands are sent to a addressed single card(addressed Command) or to all connected cards (Broad cast command).

Response:

Responses are transferred serially on the CMD line. A response is a token to answer to a previous received command. Responses are sent from a addressed single card or from all connected cards.

Data:

Data can be transfer from the card to the host or vice versa. Data is transferred via the data lines.



CLK: Host Card Clock Signal

CMD: Bi-Directional Command/Response Signal

DAT0-DAT3: 4 Bi-Directional Data Signal

V_{DD}: Power Supply

V_{SS}: GND

Figure 2: microSD Card (SD Mode) Connection Diagram

Table 3: SD Mode Command Set (+: Implemented, -: Not Implemented)

CMD	, , ,	Ineu, Not imple	,
Index	Abbreviation	Implementation	Notes
CMD0	GO_IDLE_STATE	+	
CMD2	ALL_SEND_CID	+	
CMD3	SEND_RELATIVE_ADDR	+	
CMD4	SET_DSR	-	DSR Register is not implemented
CMD6	SWITCH_FUNC	+	
CMD7	SELECT/DESELECT_CARD	+	
CMD8	SEND_IF_COND	+	
CMD9	SEND_CSD	+	
CMD10	SEND_CID	+	
CMD11	VOLTAGE_SWITCH	+	
CMD12	STOP_TRANSMISSION	+	
CMD13	SEND STATUS	+	
CMD15	GO_INACTIVE_STATE	+	
CMD16	SET BLOCKLEN	+	
CMD17	READ_SINGLE_BLOCK	+	
CMD18	READ_MULTIPLE_BLOCK	+	
CMD19	READ MULTIPLE BLOCK	+	
CMD20	SPEED_CLASS_CONTROL	+	For SDHC/SDXC
CMD23	SET BLOCK COUNT	+	For UHS104 (CMD23 does not support)
CMD24	WRITE BLOCK	+	, , ,
CMD25	WRITE MULTIPLE BLOCK	+	
CMD27	PROGRAM CSD	+	
CMD28	SET WRITE PROT	-	Internal Write Protection is not implemented.
CMD29	CLR WRITE PROT	-	Internal Write Protection is not implemented.
CMD30	SEND WRITE PROT	-	Internal Write Protection is not implemented.
CMD32	ERASE WR BLK START	+	
CMD33	ERASE WR BLK END	+	
CMD38	ERASE	+	
CMD42	LOCK_UNLOCK	+	
CMD55	APP CMD	+	
CMD56	GEN_CMD	-	This command is not specified
ACMD6	SET BUS WIDTH	+	·
ACMD13	SD STATUS	+	
ACMD22	SEND NUM WR BLOCKS	+	
ACMD23	SET_WR_BLK_ERASE_COUNT	+	
ACMD41	SD_APP_OP_COND	+	
ACMD42	SET_CLR_CARD_DETECT	+	
ACMD51	SEND_SCR	+	
ACMD18	SECURE READ MULTI BLOCK	+	
ACMD25	SECURE_WRITE_MULTI_BLOCK	+	
ACMD26	SECURE_WRITE_MKB	+	
ACMD38	SECURE_ERASE	+	
ACMD43	GET_MKB	+	
ACMD44	GET_MID	+	
ACMD45	SET_CER_RN1	+	
ACMD46	SET_CER_RN2	+	
ACMD47	SET_CER_RES2	+	
ACMD48	SET_CER_RES1	+	
ACMD49	CHANGE_SECURE_AREA	+	
	2 20 and CMD30 are Ontional Commands	Г	

- CMD28, 29 and CMD30 are Optional Commands.
 CMD4 is not implemented because DSR Register(Optional Register)
 CMD56 is for vendor specific command. Which is not defined in the standard card.

6.2.2 SPI Bus mode Protocol

The SPI bus allows 1 bit Data line by 2-channel (Data In and Out).

The SPI compatible mode allows the MMC Host systems to use SD card with little change.

The SPI bus mode protocol is byte transfers.

All the data token are multiples of the bytes (8-bit) and always byte aligned to the CS signal. The advantage of the SPI mode is reducing the host design in effort.

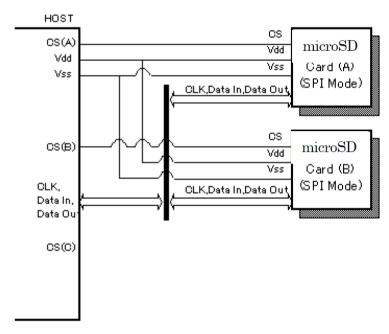
Especially, MMC host can be modified with little change.

The disadvantage of the SPI mode is the loss of performance versus SD mode.

Caution: Please use SD Card Specification. DO NOT use MMC Specification.

For example, initialization is achieved by ACMD41, and be careful with Registers.

Registers definition are different compare to MMC Specification, especially CSD Register.



CS: Card Select Signal
CLK: Host Card Clock Signal
Data In: Host to Card Data Line
Data Out: Card to Host Data Line

V_{DD}: Power Supply

V_{SS}: GND

Figure 3: microSD Card(SPI Mode) Connection Diagram

Table.4: SPI Mode Command Set (+: Implemented)

CMD Index	Abbreviation	Implementation	Notes
CMD0	GO_IDLE_STATE	+	
CMD1	SEND_OP_CND	+	NOTICE: DO NOT USE (SEE Fig.6 and 9.2)
CMD6	SWITCH_FUNC	+	
CMD8	SEND_IF_COND	+	
CMD9	SEND_CSD	+	
CMD10	SEND_CID	+	
CMD12	STOP_TRANSMISSION	+	
CMD13	SEND_STATUS	+	
CMD16	SET_BLOCKLEN	+	
CMD17	READ_SINGLE_BLOCK	+	
CMD18	READ_MULTIPLE_BLOCK	+	
CMD24	WRITE_BLOCK	+	
CMD25	WRITE_MULTIPLE_BLOCK	+	
CMD27	PROGRAM_CSD	+	
CMD28	SET_WRITE_PROT	-	Internal Write Protection is not implemented.
CMD29	CLR_WRITE_PROT	-	Internal Write Protection is not implemented.
CMD30	SEND_WRITE_PROT	-	Internal Write Protection is not implemented.
CMD32	ERASE_WR_BLK_START_ADD	+	
CMD33	ERASE_WR_BLK_END_ADDR	+	
CMD38	ERASE	+	
CMD42	LOCK_UNLOCK	+	
CMD55	APP_CMD	+	
CMD56	GEN_CMD	-	This command is not specified
CMD58	READ_OCR	+	
CMD59	CRC_ON_OFF	+	
ACMD6	SET_BUS_WIDTH	+	
ACMD13	SD_STATUS	+	
ACMD22	SEND_NUM_WR_BLOCKS	+	
ACMD23	SET_WR_BLK_ERASE_COUNT	+	
ACMD41	SD_APP_OP_COND	+	
ACMD42	SET_CLR_CARD_DETECT	+	
ACMD51	SEND_SCR	+	
ACMD18	SECURE_READ_MULTI_BLOC	+	
ACMD25	SECURE_WRITE_MULTI_BLOG	+	
ACMD26	SECURE_WRITE_MKB	+	
ACMD38	SECURE_ERASE	+	
ACMD43	GET_MKB	+	
ACMD44	GET_MID	+	
ACMD45	SET_CER_RN1	+	
ACMD46	SET_CER_RN2	+	
ACMD47	SET_CER_RES2	+	
ACMD48	SET_CER_RES1	+	
ACMD49	CHANGE_SECURE_AREA	+	

- CMD28, 29 and CMD30 are Optional Commends.
- > CMD56 is for vender specific command. Which is not defined in the standard card.

6.3. microSD Card Initialize

Fig.4-1 shows initialization flow chart for UHS-I hosts and Fig.4-2 shows sequence of commands to perform signal voltage switch. Red and yellow boxes are new procedure to initialize UHS-I card.

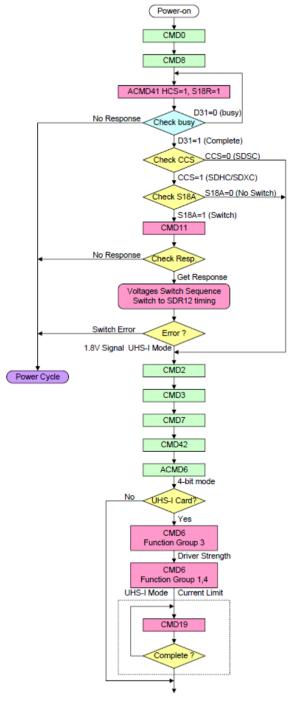


Figure 4-1: UHS-I Host Initialization Flow Diagram

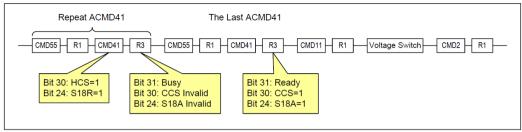


Figure 4-2: ACMD41 Timing Followed by Signal Voltage Switch Sequence

1) POWER ON: Supply Voltage for initialization.

Host System applies the Operating Voltage to the card.

Apply more than 74 cycles of Dummy-clock to the microSD card.

2) Select operation mode (SD mode or SPI mode)

In case of SPI mode operation, host should drive 1 pin (CD/DAT3) of SD Card I/F to "Low" level. Then, issue CMD0.

In case of SD mode operation, host should drive or detect 1 pin of SD Card I/F (Pull up register of 1 pin is pull up to "High" normally).

Card maintain selected operation mode except re-issue of CMD0 or power on below is SD mode initialization procedure.

3) Send Interface condition command (CMD8).

When the card is in Idle state, the host shall issue CMD8 before ACMD41.

In the argument, 'voltage supplied' is set to the host supply voltage and 'check pattern' is set to any 8-bit pattern.

The card that accepted the supplied voltage returns R7 response.

In the response, the card echoes back both the voltage range and check pattern set in the argument.

If the card does not support the host supply voltage, it shall not return response and stays in Idle state.

4) Send initialization command (ACMD41).

When signaling level is 3.3V, host repeats to issue ACMD41 with HCS=1 and S18R=1 until the response indicates ready.

The argument (HCS and S18R) of the first ACMD41 is effective but the all following ACMD41 should be issued with the same argument.

If Bit 31 indicates ready, host needs to check CCS and S18A.

The card indicates S18A=0, which means that voltage switch is not allowed and the host needs to use current signaling level.

-			
Current Signaling Level	18R	S18A	Comment
	0	0	1.8V signaling is not requested
3.3V	1	0	The card does not support 1.8V signaling
	1	1	Start signal voltage switch sequence
1.8V	X	0	Already switched to 1.8V

Table 5: S18R and S18A Combinations

5) Send voltage switch command (CMD11).

S18A=1 means that voltage switch is allowed and host issues CMD11 to invoke voltage switch sequence.

By receiving CMD11, the card returns R1 response and start voltage switch sequence.

No response of CMD11 means that S18A was 0 and therefore host should not have sent CMD11.

Completion of voltage switch sequence is checked by high level of DAT[3:0].

Any bit of DAT[3:0] can be checked depends on ability of the host.

The card enters UHS-I mode and card input and output timings are changed (SDR12 in default) when the voltage switch sequence is completed successfully.

- 6) Send ALL SEND CID command (CMD2) and get the Card ID (CID).
- 7) Send SEND RELATIVE ADDR (CMD3) and get the RCA.

RCA value is randomly changed by access, not equal zero.

8) Send SELECT / DESELECT_CARD command (CMD7) and move to the transfer state.

When entering tran state, CARD_IS_LOCKED status in the R1 response should be checked (it is indicated in the response of CMD7).

If the CARD_IS_LOCKED status is set to 1 in the response of CMD7, CMD42 is required before ACMD6 to unlock the card.

(If the card is locked, CMD42 is required to unlock the card.)

If the card is unlocked, CMD42 can be skipped.

9) Send SET_BUS_WIDTH command (ACMD6).

UHS-I supports only 4-bit mode. Host shall select 4-bit mode by ACMD6.

If the card is locked, host needs to unlock the card by CMD42 in 1-bit mode and then needs to issue ACMD6 to change

4-bit bus mode. Operating in 1-bit mode is not assured.

10) Set driver strength.

CMD6 mode 0 is used to query which functions the card supports, and to identify the maximum current consumption of the card under the selected functions.

In case of UHS-I card, appropriate driver strength (default is Type-B buffer) is selected by CMD6 Function Group 3.

11) Set UHS-I mode current limit.

UHS-I modes (Bus Speed Mode) is selected by CMD6 Function Group 1.

Current Limit is selected by CMD6 Function Group 4.

Maximum access settings:

SDR50 = (CMD6 Function Group 1 = 2-h, CMD6 Function Group 4 = 1-h)

Note:

Function Group 4 is defined as Current Limit switch for SDR50.

The Current Limit does not act on the card in SDR12 and SDR25.

The default value of the Current Limit is 200mA (minimum setting).

Then after selecting one of SDR50 mode by Function Group 1, host needs to change the Current Limit to enable the card to operate in higher performance.

This value is determined by a host power supply capability to the card, heat release method taken by a host and the maximum current of a connector.

12) Tuning of sampling point

CMD19 sends a tuning block to the host to determine sampling point.

In SDR50 and SDR104 modes, if tuning of sampling point is required, CMD19 is repeatedly issued until tuning is completed

Then the Host can access the Data between the SD card as a storage device.

6.4. microSD Card Electrical Characteristics

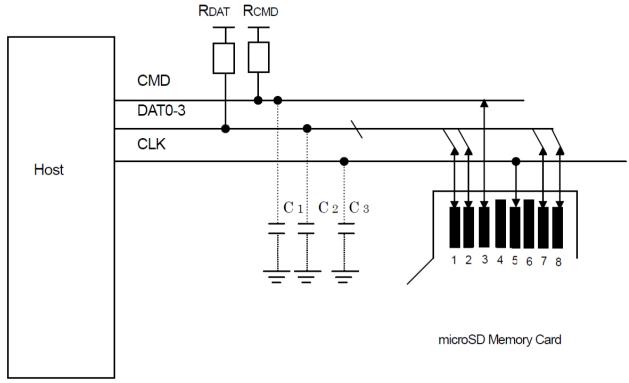


Figure 5: microSD Card Connection Diagram

6.4.1 DC Characteristics

Table 6-1: DC Characteristics (Threshold level for High Voltage Range)

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Supply Vo	ltage	V_{DD}	-	2.7	-	3.6	V	
Input	High Level	V_{IH}	-	V _{DD} *0.625	-	-	V	
Voltage	Low Level	V_{IL}	-	-	-	V _{DD} *0.25	V	
Output	High Level	V_{OH}	$I_{OH} = -2mA$	V _{DD} *0.75	-	-	٧	
Voltage	Low Level	V_{OL}	$I_{OL} = 2mA$	-	-	V _{DD} *0.125	V	
Power	Up Time		-	-	-	250	ms	0V to V _{DD} min

^{*)} Peak Current: RMS value over a 10 usec period

Table 6-2: Peak Voltage and Leakage Current

Parameter	Symbol	Min.	Max.	Unit	Note
Peak Voltage on All Lines		-0.3	V _{DD} +0.3	V	
All Inputs		•	•		
Input Leakage Current		-10	10	uA	
All Outputs		•	•		
Output Leakage Current		-10	10	uA	

Table 6-3: DC Characteristics (Threshold Level for 1.8V Signaling)

Item		Symbol	Min.	Max.	Unit	Condition
Supply Voltage		V_{DD}	2.7	3.6	V	
Regulator Voltage)	V_{DDIO}	1.7	1.95	V	Generated from V _{DD}
Input Voltage	High Level	V_{IH}	1.27	2.00	V	
Input voltage	Low Level	V_{IL}	V_{SS} -0.3	0.58	V	
Output Voltage	High Level	V _{OH}	1.4	-	V	
Output Voltage	Low Level	V_{OL}	-	0.45	V	

Table 6-4: Input Leakage Current for 1.8V Signaling

Parameter	Symbol	Min.	Max.	Unit	Note
Input Leakage Current		-2	2	uA	DAT3 Pull-Up is Disconnected

Table 6-5: Power Consumption

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Standby Current	I _{ccs}	3.0V Clock Stop	-	-	950	uA	@ 25°C
		Current Limit=400mA	-	-	300		
		V _{DD} =3.6V					
Operation	I _{CCOP1}	Current Limit=200mA	-	-	300		@ 25°C
Current(Peak)	*1)	V _{DD} =3.6V				mA	@ 25 C
		(HS or DS)	-	-	300		
		V _{DD} =3.6V					
		Current Limit=400mA	-	-	250		
		V _{DD} =3.6V					
		Current Limit=200mA	-	-	200		
Operation	I _{CCOP2}	V _{DD} =3.6V				mA	@ 25°C
Current(Average)	*2)	(SDR25 or HS)	-	-	200	ША	W 23 C
		V _{DD} =3.6V					
		(SDR12.5 or DS)	-	-	100		
		V _{DD} =3.6V					

^{*1)} Peak Current: RMS value over a 10usec period *2) Average Current: value over 1 sec period.

Table 6-6: Signal Capacitance

Total Bus Capacitance = $C_{HOST} + C_{BUS} + N*C_{Card}$

Item	Symbol	Min.	Max.	Unit	Note
Pull-Up Resistance	R _{CMD} R _{DAT}	10	100	K Ohm	
Total Bus Capacitance for Each Signal Line	C _L	-	40	pF	1 Card C _{HOST} +C _{BUS} Shall Not Exceed 30pF
Card Capacitance for Each Signal Pin	C_{CARD}	-	10	pF	
Maximum Signal Line Inductance		-	16	nH	
Pull-Up Resistance Inside Card(Pin 1)	R _{DAT3}	10	90	K Ohm	May Be Used for Card Detection
Capacity Connected to Power Line	C _C	-	5	uF	To Prevent Inrush Current

Note: WP pull-up (R_{wp}) Value is depend on the Host Interface drive circuit.

6.4.2 AC Characteristics (Default)

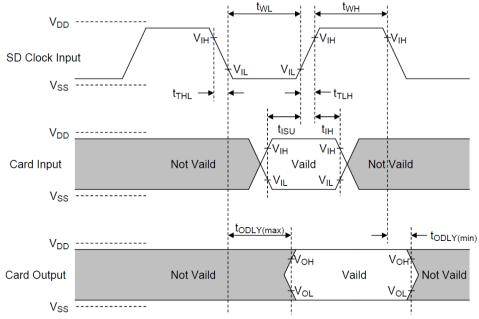


Figure 6-1: AC Timing Diagram (Default)

Table 7-1: AC Characteristics (Default)

Item	Symbol	Min.	Max.	Únit	Note
Clock Frequency (In Any State)	f _{STP}	0	25	MHz	
Clock Frequency (Data Transfer Mode)	f_{PP}	0	25	MHz	
Clock Frequency (Card Identification Mode)	f_{OD}	0/100(*1)	400	KHz	C _{CARD} ≤ 10pF
Clock Low Time	t _{WL}	10	1	ns	(1 Card)
Clock High Time	t _{WH}	10	ı	ns	
Clock Rise Time	t _{TLH}	-	10	ns	
Clock Fall Time	t _{THL}	-	10	ns	
Input Set-up Time	t _{ISU}	5	ı	ns	
Input Hold Time	t _{IH}	5	ı	ns	
Output Delay Time	t	0	14	ns	
(Data Transfer Mode)	t _{ODLY}	0	14	113	C _L ≤ 40pF
Output Delay Time (Identification Mode)	t _{ODLY}	0	50	ns	(1 Card)

^{(*1) 0}Hz means to stop the clock. The given minimum frequency range is for cases were continues clock is required.

6.4.3 AC Characteristics (High-Speed)

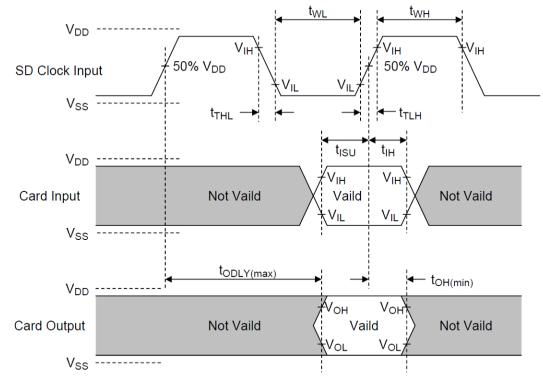


Figure 6-2: AC Timing Diagram (High-Speed)

Table 7-2: AC Characteristics (High-Speed)

Table 7-2. AC Characteristics (Figit-Speed)							
Item	Symbol	Min.	Max.	Unit	Note		
Clock Frequency	4	0	50	N/I I -	C < 10 p F (1 C and)		
(Data Transfer Mode)	f _{PP}	0	50	MHz	C _{CARD} ≤ 10pF (1 Card)		
Clock Low Time	t _{WL}	7	-	ns	C _{CARD} ≤ 10pF (1 Card)		
Clock High Time	t _{WH}	7	-	ns	C _{CARD} ≤ 10pF (1 Card)		
Clock Rise Time	t _{TLH}	-	3	ns	C _{CARD} ≤ 10pF (1 Card)		
Clock Fall Time	t _{THL}	-	3	ns	C _{CARD} ≤ 10pF (1 Card)		
Input Set-up Time	t _{ISU}	6	-	ns	C _{CARD} ≤ 10pF (1 Card)		
Input Hold Time	t _{IH}	2	-	ns	C _{CARD} ≤ 10pF (1 Card)		
Output Delay Time	+		14	nc	$C_{CARD} \le 10pF (1 Card)$		
(Data Transfer Mode)	t _{ODLY}	_	14	ns	CCARD & TOPF (1 Cald)		
Output Hold Time	T _{OH}	2.5	-	ns	C _{CARD} ≤ 10pF (1 Card)		
Total System Capacitance	C∟	-	40	pF	C _{CARD} ≤10pF (1 Card)		

6.4.4 AC Characteristics (SDR12, SDR25, SDR50, and SDR104 Modes)

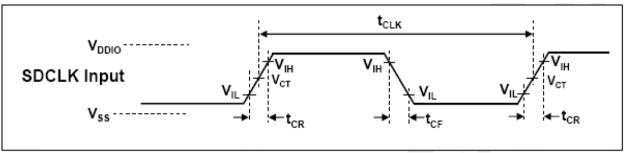


Figure 6-3: AC Timing Diagram (SDR12, SDR25, SDR50, and SDR104 Modes Input)

Table 7-3: AC Characteristics (SDR12, SDR25, SDR50, and SDR104 Modes Input)

Symbol	Min.	Max.	Unit	Remark
t _{CLK}	4.80	-	ns	208MHz(Max.), between rising edge, V _{CT} =0.975V
t_{CR}, t_{CF}	-	0.2*t _{CLK}	ns	t_{CR} , t_{CF} < 2.00ns(Max.) at 100MHz, C_{CARD} = 10pF
Clock Duty	30	70	%	

7. Card Internal Information

7.1. Security Information

MKB (Media Key Block) and Media ID are Kingston Standard Information. These information are compliance with the CPRM.

Note: The security information is NOT Development information for evaluation. Host System shall be compliance with the CPRM to use the security function.

This information is kept as confidential because of security reasons.

7.2. SD Card Registers

The device has six Registers and two Status information: OCR, CID, CSD, RCA, DSR, SCR and Card Status, SD Status same with Card Status. DSR IS NOT SUPPORTED in this card. There are two types of register groups.

MMC compatible registers: OCR, CID, CSD, RCA, DSR, and SCR SD card Specific: SD Status and Card Status

Table 8: SD card Registers

Register Name	Bit Width (bit)	Description
CID	128	Card Indentification
RCA	16	Relative Card Address
DSR	16	Driver Stage Register
CSD	128	Card Specific Data
SCR	64	SD Configuration Register
OCR	32	Operation Conditions Register
SSR	512	SD Status
CSR	32	Card Status Register

7.2.1 OCR Register

This 32-bit register describes operating voltage range and status bit in the power supply.

Table 9: OCR Register Definition

OCR bit		OCP Fields Polition	Response Value
Position		OCR Fields Defition	64GB
0-3		Reserved	0
4-6		Reserved	0
7		Reserved for Low Voltage Range	0
8-14	∂	Reserved	0
15	VDD Voltage Window	2.8 ~ 2.7	1
16	≥	2.9 ~ 2.8	1
17	ge	3.0 ~ 2.9	1
18] 쁑	3.1 ~ 3.0	1
19] >	3.2 ~ 3.1	1
20] j	3.3 ~ 3.2	1
21	7 >	3.4 ~ 3.3	1
22		3.5 ~ 3.4	1
23		3.6 ~ 3.5	1
24 ¹	Switc	hing to 1.8V Accepted (S18A)	1
25-29	Rese	rved	0
30	Card	Capacity Status(CCS) ²	1
31	Card	Power Up Status bit (Busy) ³	"0" = Busy "1" = Ready

- (1) bit24: Only UHS-I card supports this bit.
- (2) bit30 : This bit is valid only when the card power up status bit is set.
- (3) bit31: This bit is set to LOW if the card has not finished the power up routine.
- bit 23-4: Describes the SD Card Voltage

bit 31 indicates the card power up status. Value "1" is set after power up and initialization procedure has been completed.

7.2.2 CID Register

The CID (Card Identification) register is 128-bit width. It contains the card identification information. The Value of CID Register is vendor specific.

Table 10: CID Register

Name	Field	Width	CID-Slice	Initial Value
Name	Fleid Width Cib-Slice		CID-Slice	64GB
Manufacturer ID	MID	8	[127:120]	41h
OEM/Application ID	OID	16	[119:104]	3432h
Product Name	PNM	40	[103:64]	SDCIT
Product Revision	PRV	8	[63:56]	30h
Product Serial Number	PSN	32	[55:24]	PSN ^A
Reserved		4	[23:20]	
Manufacturing Date	MDT	12	[19:8]	MDT ^B
CRC7 Checksum	CRC	7	[7:1]	CRC ^C
Not Used, Always 1	-	1	[0:0]	1

⁽A), (B): Change at Production for individual SD Card. (C) Final sum for the CID Register

7.2.3 CSD Register

CSD is Card-Specific Data Register provides information on 128bit width.

Table 11: CSD Register

		11. 0001	Cell	CSD-	Initial Value
Name	Field	Width	Type	Slice	64GB
CSD Structure	CSD STRUCTURE	2	R	[127:126]	0x01
Reserved	-	6	R	[125:120]	0x00
Data Read Access-Time-1	TAAC	8	R	[119:112]	0x0E
Data Read Access-Time-2 in CLK Cycles (NSAC*100)	NSAC	8	R	[111:104]	0x00
Max. Data Transfer Rate	TRAN_SPEED	8	R	[103:96]	0x5A
Card Command Classes	CCC	12	R	[95:84]	0x5B5
Max. Read Data Block Length	READ_BL_LEN	4	R	[83:80]	0x09
Partial Blocks for Read Allowed	READ_BL_PARTIAL	1	R	[79:79]	0x00
Write Block Misalignment	WRITE_BLK_MISALIGN	1	R	[78:78]	0x00
Read Block Misalignment	READ_BLK_MISALIGN	1	R	[77:77]	0x00
DSR Implemented	DSR_IMP	1	R	[76:76]	0x00
Reserved	-	6	R	[75:70]	0x00
Device Size	C_SIZE	22	R	[69:48]	0x01D27F
Reserved	-	1	R	[47:47]	0x00
Erase Single Block Enable	ERASE BLK EN	1	R	[46:46]	0x01
Erase Sector Size	SECTOR SIZE	7	R	[45:39]	0x7F
Write Protect Group Size	WP_GRP_SIZE	7	R	[38:32]	0x00
Write Protect Group Enable	WP_GRP_ENABLE	1	R	[31:31]	0x00
Reserved (Do Not Use)	-	2	R	[30:29]	0x00
Write Speed Factor	R2W_FACTOR	3	R	[28:26]	0x02
Max. Write data Block Length	WRITE_BL_LEN	4	R	[25:22]	0x09
Partial Blocks for Write Allowed	WRITE_BL_LEN	1	R	[21:21]	0x00
Reserved	-	5	R	[20:16]	0x00
File Format Group	FILE_FORMAT_GRP	1	R	[15:15]	0x00
Copy Flag	COPY	1	R/W ⁽¹⁾	[14:14]	0x00
Permanent Write Protection	PERM_WRITE_PROTEC T	1	R/W ⁽¹⁾	[13:13]	0x00
Temporary Write Protection	TMP_WRITE_PROTECT	1	R/W	[12:12]	0x00
File Format	FILE_FORMAT	2	R	[11:10]	0x00
Reserved	-	2	R	[9:8]	0x00
CRC	CRC	7	R/W	[7:1]	CRC
Not Used, Always "1"	-	1	-	[0:0]	0x01

Cell Types: R: Read Only, R/W: Readable and Writable, R/W(1): One-time Writable / Readable

Note: Erase of one data block is not allowed in this card. This information is indicated by "ERASE_BLK_EN". Host System should refer this value before one data block size erase.

7.2.4 RCA Register

The Writable 16-bit relative card address register carries the card address in SD Card mode.

7.2.5 DSR Register

This register is not supported.

7.2.6 SCR Register

SCR(SD Card Configuration Register) provides information on SD Memory Card's special features. The size of SCR Register is 64 bit.

Table 12: SCR Register

Description	Field	Width	Cell	SCR	Value
Description	i leid	VVIGUI	Type	Slice	64GB
SCR Structure	SCR_STRUCTURE	4	R	[63:60]	0x00
SD Memory Card Spec. Version	SD_SPEC	4	R	[59:56]	0x02
Data Status After Erases	DATA_STAT_AFTER_ERAS E	1	R	[55:55]	0x00
CPRM Security Support	SD_SECURITY	3	R	[54:52]	0x04
DAT Bus Widths Supported	SD_BUS_WIDTHS	4	R	[51:48]	0x05
Spec. Version 3.00 or Higher	SD_SPEC3	1	R	[47:47]	0x01
Extended Security Support	EX_SECURITY	4	R	[46:43]	0x00
Spec Version 4.00 or Higher	SD_SPEC4	1	R	[42:42]	0x00
Reserved	-	6	R	[41:36]	0x00
Command Support Bits	CMD_SUPPORT	4	R	[35:32]	0x03
Reserved for Manufacturer Usage	-	32	R	[31:0]	0x01 0x00 0x00 0x00

7.2.7 Card Status

Table 13: Card Status

		able 10: Cara		Value
Field	Width	SCR Slice	Type	64GB
OUT OF RANGE	1	[31:31]	ERX	0
ADDRESS ERROR	1	[30:30]	ERX	0
BLOCK LEN ERROR	1	[29:29]	ERX	0
ERASE_SEQ_ERROR	1	[28:28]	ER	0
ERASE_PARAM_ERROR	1	[27:27]	ERX	0
WP_VIOLATION:PROTECTED	1	[26:26]	ERX	0
CARD_IS_LOCKED	1	[25:25]	SX	0
LOCK_UNLOCK_FAIL	1	[24:24]	ERX	0
COM_ECC_ERROR	1	[23:23]	ER	0
ILLEGAL_COMMAND	1	[22:22]	ER	0
CARD_ECC_FAILED	1	[21:21]	ERX	0
CC_ERROR	1	[20:20]	ERX	0
General or Unknown ERROR	1	[19:19]	ERX	0
Reserved	1	[18:18]	-	0
Reserved	1	[17:17]	-	0
CSD_OVERWRITE	1	[16:16]	ERX	0
WP_ERASE_SKIP:PROTECTED	1	[15:15]	ERX	0
CARD_ECC_DISABLED	1	[14:14]	SX	0
ERASE_RESET	1	[13:13]	SR	0
CURRENT_STATE	4	[12:9]	SX	4
READY_FOR_DATA	1	[8:8]	SX	1
Reserved	1	[7:7]	-	0
FX_EVENT	1	[6:6]	SX	0
APP_CMD	1	[5:5]	S	0
Reserved	1	[4:4]	R	0
AKE_SEQ_ERROR	1	[3:3]	ER	0
Reserved	1	[2:2]	-	0
Reserved	1	[1:1]	-	0
Reserved	1	[0:0]	-	0

E: Error bit , S: Status bit , R: Detected and set for actual command response.
X: Detected and set during command execution.

Appendix: microSD Card Mechanical Dimensions (Unit: mm)

